



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



MC100LVEL32

3.3 V ECL ÷2 Divider

Description

The MC100LVEL32 is an integrated ÷2 divider. The LVEL32 is functionally identical to the EL32, but operates from a 3.3 V supply.

The reset pin is asynchronous and is asserted on the rising edge. Upon power-up, the internal flip-flop will attain a random state; the reset allows for the synchronization of multiple LVEL32's in a system.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- 510 ps Propagation Delay
- 2.6 GHz Typical Maximum Frequency
- ESD Protection:
 - ◆ > 4 KV Human Body Model
 - ◆ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range:
 - $V_{CC} = 3.0 \text{ V to } 3.8 \text{ V}$ with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range:
 - $V_{CC} = 0 \text{ V}$ with $V_{EE} = -3.0 \text{ V to } -3.8 \text{ V}$
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity:
 - ◆ Level 1 for SOIC-8
 - ◆ Level 3 for TSSOP-8
 - ◆ Level 1 for DFN-8
 - ◆ For Additional Information, see Application Note [AND8003/D](#)
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 111 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



ON Semiconductor®

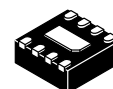
www.onsemi.com



SOIC-8 NB
D SUFFIX
CASE 751-07

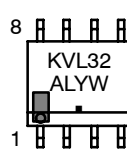


TSSOP-8
DT SUFFIX
CASE 948R-02

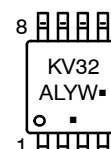


DFN-8
MN SUFFIX
CASE 506AA

MARKING DIAGRAMS*



SOIC-8 NB



TSSOP-8



DFN-8

- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL32DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
MC100LVEL32DR2G	SOIC-8 NB (Pb-Free)	2500 Tape & Reel
MC100LVEL32DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
MC100LVEL32DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel
MC100LVEL32MNR4G	DFN-8 (Pb-Free)	1000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MC100LEVEL32

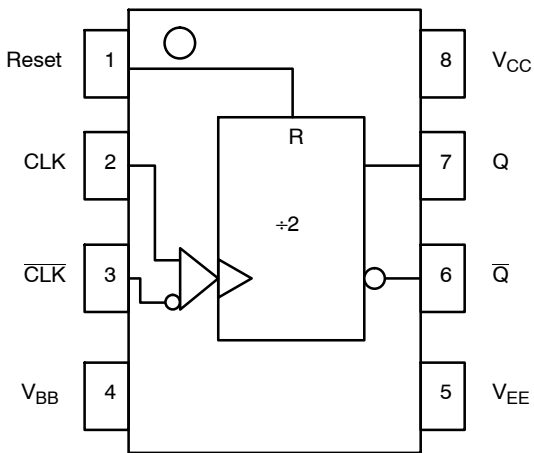


Figure 1. Logic Diagram and Pinout Assessment

Table 1. PIN DESCRIPTION

Pin	Function
CLK*, $\overline{\text{CLK}}^{**}$	ECL Differential Clock Inputs
Q, $\overline{\text{Q}}$	ECL Differential Data +2 Outputs
Reset*	ECL Asynch Reset
V_{BB}	Reference Voltage Output
V_{CC}	Positive Supply
V_{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

*Pin will default low when left open, per internal 75 K pull-down to V_{EE} .

** Pin will default to $V_{\text{CC}}/2$ when left open per internal 75 K Ω pull-down to V_{EE} and 75 K Ω pull-up to V_{CC} .

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	$V_{\text{EE}} = 0 \text{ V}$		8 to 0	V
V_{EE}	NECL Mode Power Supply	$V_{\text{CC}} = 0 \text{ V}$		-8 to 0	V
V_{I}	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{\text{EE}} = 0 \text{ V}$ $V_{\text{CC}} = 0 \text{ V}$	$V_{\text{I}} \leq V_{\text{CC}}$ $V_{\text{I}} \geq V_{\text{EE}}$	6 to 0 -6 to 0	V
V_{I}	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{\text{EE}} = 0 \text{ V}$ $V_{\text{CC}} = 0 \text{ V}$	$V_{\text{I}} \leq V_{\text{CC}}$ $V_{\text{I}} \geq V_{\text{EE}}$	6 to 0 -6 to 0	V
I_{out}	Output Current	Continuous Surge		50 100	mA
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_{A}	Operating Temperature Range			-40 to +85	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range			-65 to +150	$^{\circ}\text{C}$
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB SOIC-8 NB	190 130	$^{\circ}\text{C}/\text{W}$
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44 $\pm 5\%$	$^{\circ}\text{C}/\text{W}$
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	$^{\circ}\text{C}/\text{W}$
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 $\pm 5\%$	$^{\circ}\text{C}/\text{W}$
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN-8 DFN-8	129 84	$^{\circ}\text{C}/\text{W}$
T_{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260 $^{\circ}\text{C}$		265	$^{\circ}\text{C}$
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN-8	35 to 40	$^{\circ}\text{C}/\text{W}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

MC100LEVEL32

Table 3. LVPECL DC CHARACTERISTICS ($V_{CC} = 3.3\text{ V}$; $V_{EE} = 0.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		31	36	mA
V_{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3) $V_{PP} < 500\text{ mV}$ $V_{PP} \geq 500\text{ mV}$	1.2 1.4		3.1 3.1	1.1 1.3		3.1 3.1	1.1 1.3		3.1 3.1	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $\pm 0.3\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PPmin} and 1 V .

Table 4. LVNECL DC CHARACTERISTICS ($V_{CC} = 0.0\text{ V}$; $V_{EE} = -3.3\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		31	36	mA
V_{OH}	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V_{OL}	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V_{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3) $V_{PP} < 500\text{ mV}$ $V_{PP} \geq 500\text{ mV}$	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $\pm 0.3\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PPmin} and 1 V .

MC100LVEL32

Table 5. AC CHARACTERISTICS ($V_{CC} = 3.3\text{ V}$; $V_{EE} = 0.0\text{ V}$ or $V_{CC} = 0.0\text{ V}$; $V_{EE} = -3.3\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{\max}	Maximum Toggle Frequency	2.2	2.5		2.4	2.6		2.6	2.8		GHz
t_{PLH} t_{PHL}	Propagation Delay CLK to Q (Differential) CLK to Q (Single-Ended) Reset to Q	350 300 440	500 500 555	530 580 640	370 320 450	510 510 540	550 600 650	410 360 480	540 540 580	590 640 680	ps
t_{RR}	Reset Recovery	175	50		175	50		175	50		ps
t_{PW}	Minimum Pulse Width Reset	500	300		500	300		500	300		ps
t_{JITTER}	Random Clock Jitter (RMS)		2.0			2.0			2.0		ps
V_{PP}	Input Swing (Differential Swing) (Note 2)	150		1000	150		1000	150		1000	mV
t_r t_f	Output Rise / Fall Times Q (20%–80%)	120	225	320	120	225	320	120	225	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{EE} can vary $\pm 0.3\text{ V}$.
2. $V_{PP}(\min)$ is input swing measured single-ended on each input in differential configuration.

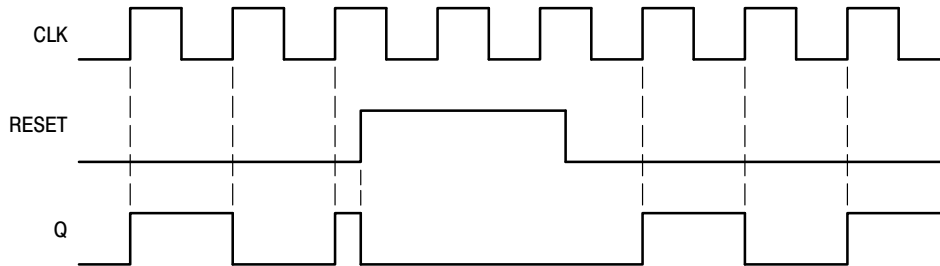


Figure 1. Timing Diagram

MC100LVEL32

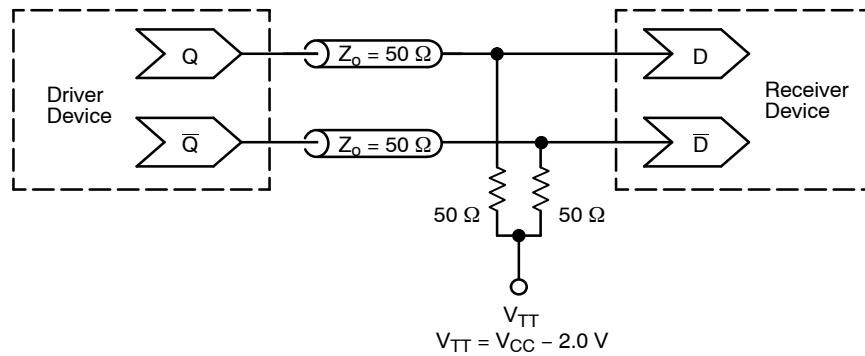


Figure 2. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)

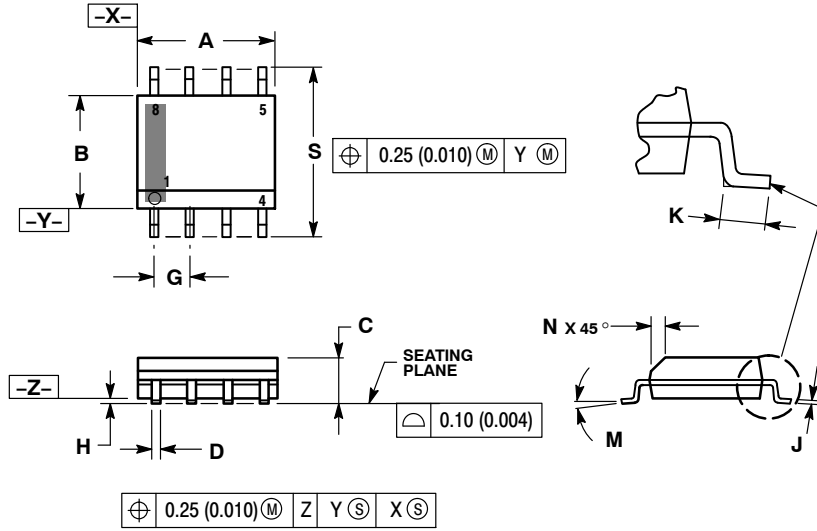
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MC100LEVEL32

PACKAGE DIMENSIONS

SOIC-8 NB
D SUFFIX
CASE 751-07
ISSUE AK

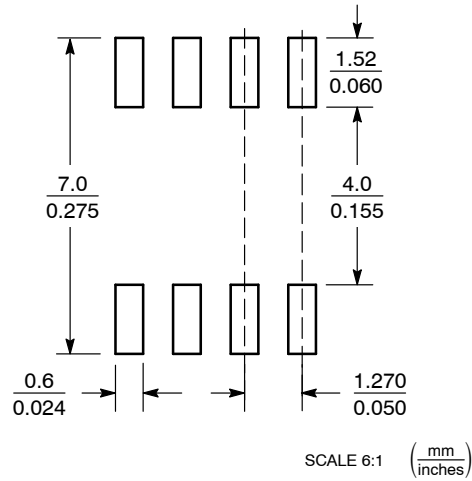


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

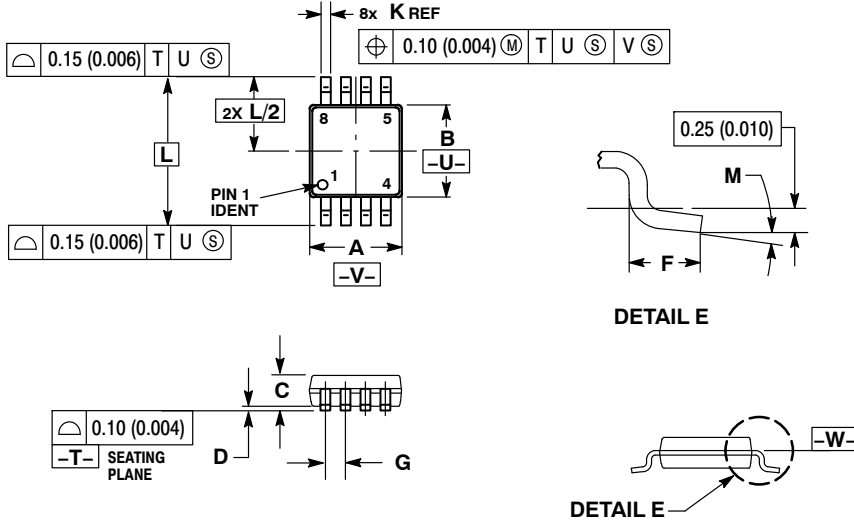


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC100LVEL32

PACKAGE DIMENSIONS

TSSOP-8
DT SUFFIX
CASE 948R-02
ISSUE A



NOTES:

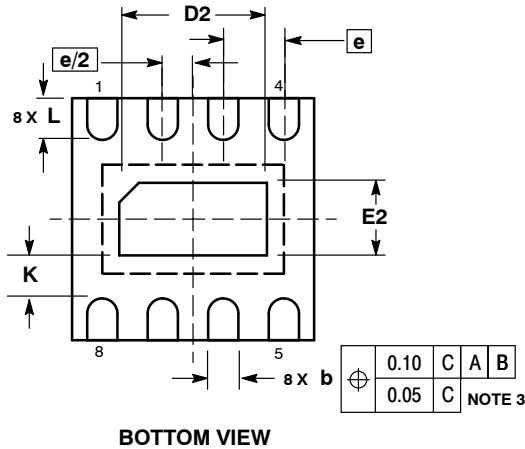
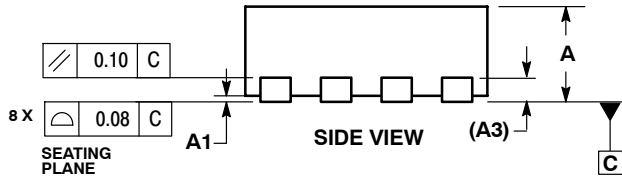
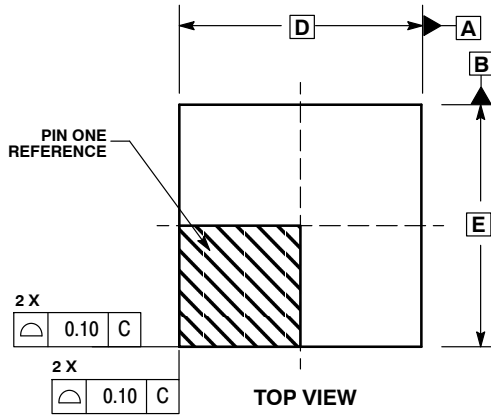
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

MC100LVEL32

PACKAGE DIMENSIONS

DFN-8
MN SUFFIX
CASE 506AA
ISSUE D



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.20	---
L	0.25	0.35

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative